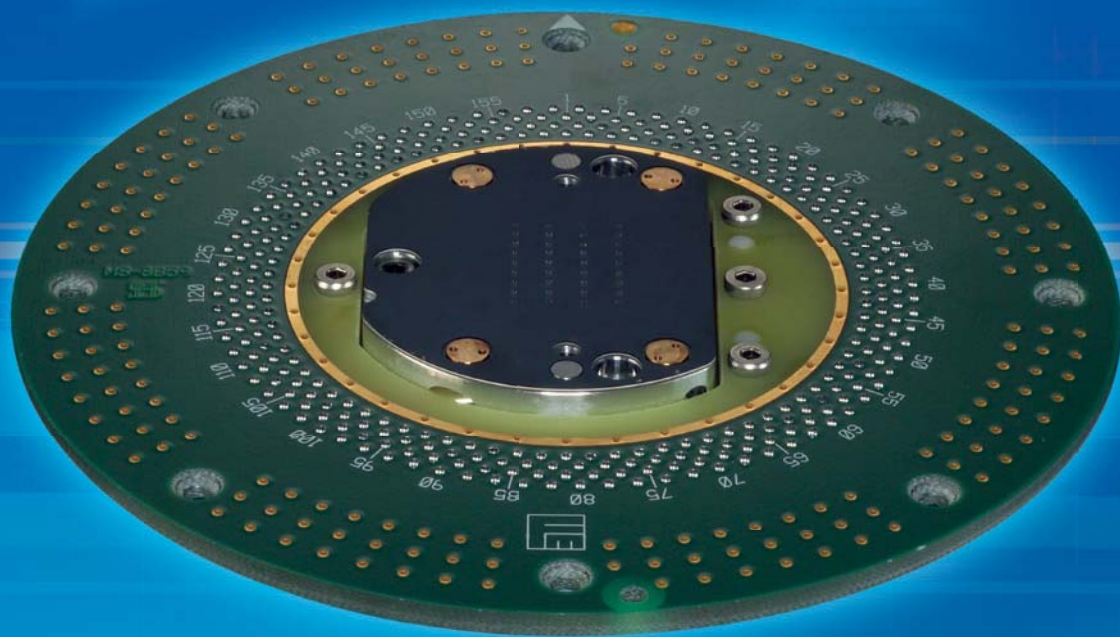


ViProbe® Wired Series

Probe Cards for Wafer Test



FEINMETALL

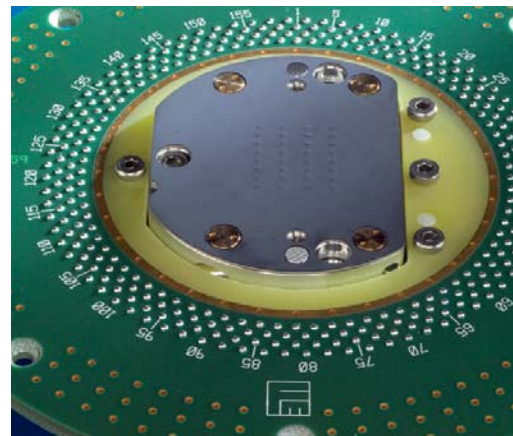
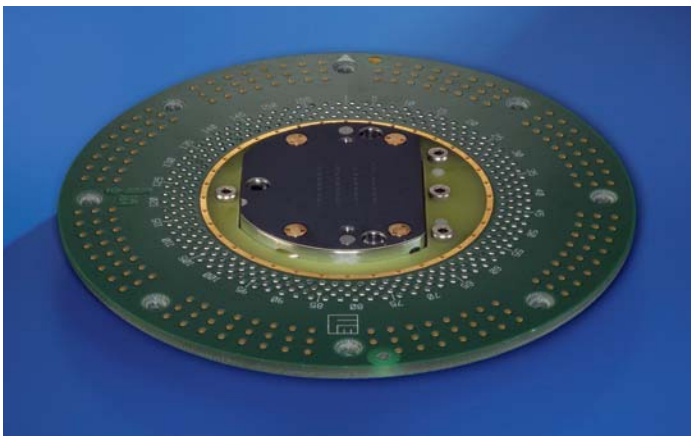
Contact technologies for electronics



ViProbe® Wired Series

FEINMETALL ViProbe® Wired Series represents a technology in advanced wafer probing. The advantages of our ViProbe® Wired Series are fast lead time, high flexibility as well as flexible probe tip depth.

ViProbe® Wired Series products are based on Wired Version Technology. These products provide the capability for substantial time- and cost- savings in wafer testing.



7 good reasons for using ViProbe® Wired Series the Vertical Probe Card Technology from Feinmetall

- Fast lead time and flexibility
- Easy Maintenance & Service
- Easy exchange of needles
- Precise alignment over the entire lifetime
- Excellent temperature behaviour
- Minimum impact on the bond pad
- Tolerates changing planarity conditions

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Key Parameters	W10/W01/W02/ W41/W42/W43
Active Area:	from 10x10mm (W10) to 45x45mm (W43)
Tester:	Teradyne J750, µFlex Verigy V93000 all other testers possible
Pitch:	min 59µm
Test points:	up to 3,500
Temperature:	-40°C...+180°C

Subject to change without notice

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